Recently memory module failure related with TSOP, FBGA or 4 array resistor crack has increased.
Main root causes are mechanical damage caused by wrong handling method.
Current products have more capacitors and resistors, those sizes are reduced and in addition, most of them are mainly located around edge parts of memory module PCB.
Because of the above characteristics, memory module should be handled more cautiously.
Samsung recommend that customer should handle memory module in accordance to following handling guide
Classification

TSOP Type

Unbuffered DIMM

Registered DIMM

SODIMM

FBGA Type
Proper Handling

Anti-ESD Strap or ESD safe work mat should be applied.

Memory module should be picked up from packing tray only one by one.

Please hold it gently with two hands.
Proper Handling

Place a memory module gently on the socket in both hands.

Press both top sides of PCB as left thumb, separately.

Insert one top side of PCB and then insert the other side.

(ex 1 → 2 or 2 → 1)
Wrong Handling

Do not stack two or more memory modules

Do not grasp two or more memory modules at one time.
Wrong Handling

Do not drop memory modules to the floor.

Handling memory modules near to tool jig is prohibited because Rigid Metals can give memory modules damage.
Wrong Handling

Do not twist or bow a memory module

Do not stack memory modules in a hand
Wrong Handling

Do not insert with holding packages and passive elements, it can cause package cracks and detachment of passive elements by higher inserting force.

Insert only one memory module at one time, do not insert multiple memory module at the same time.

Do not press both sides of PCB at the same time.

Pressing with both hands at the same time may cause solder joint cracks and package cracks by memory module twist and bow, because Inserting force in both sides at the same time is higher about two times than one given separately.